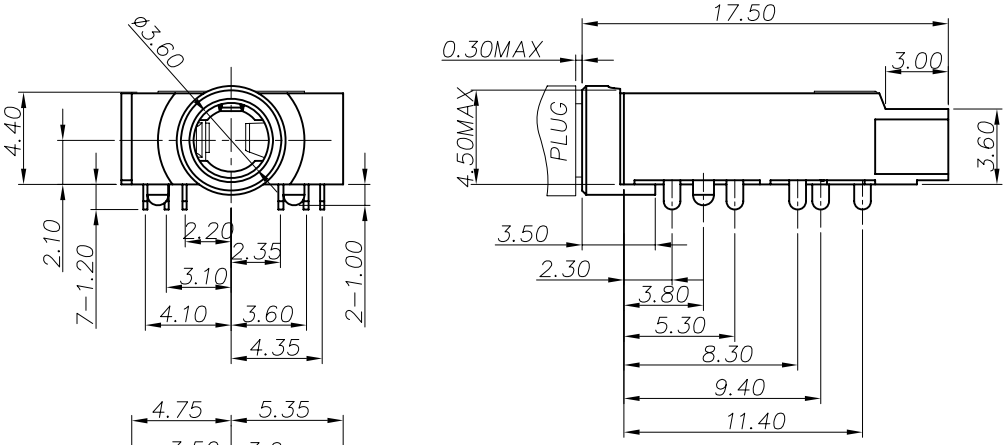
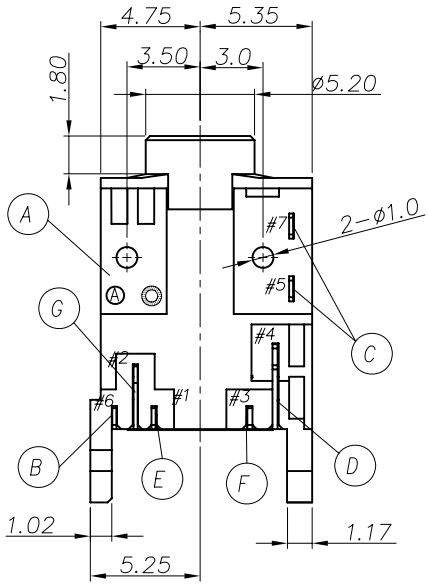
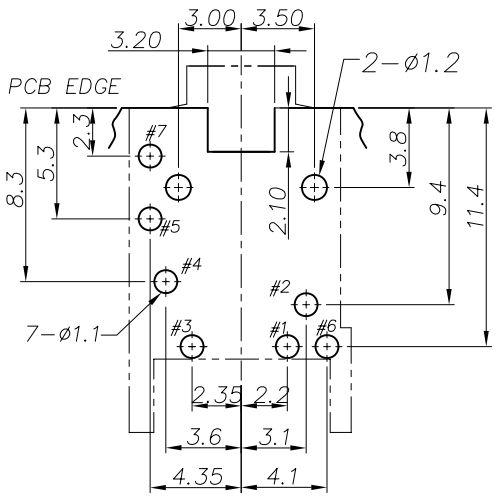
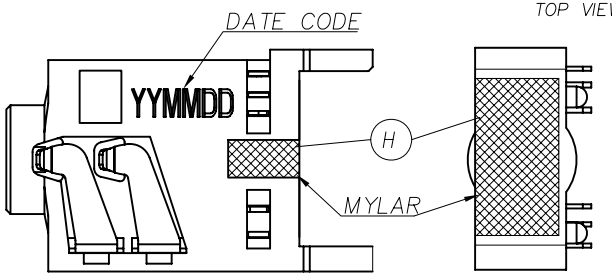
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO.T081118-2A	LILI	2008.12.16
B	ECN NO.S090503	Tom	2009.04.30
C	ECN NO.S091101	Allen	2009.12.10





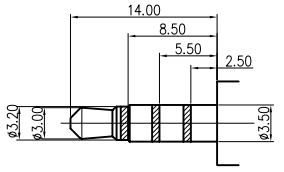


RECOMMENDED PCB LAYOUT
TOP VIEW (TOLERANCE: ±0.05)

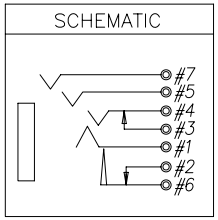


SPECIFICATIONS :

1. INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC MEGGER.
2. CONTACT RESISTANCE : 30mΩ MAX.
3. INSULATION VOLTAGE WITHSTAND : 500V AC FOR ONE MINUTE.
4. UNLESS OTHERWISE SPECIFIED. TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
5. LIFE TEST : 5,000 CYCLES MIN. (NON-LOAD)
6. INSERTION FORCE :0.4 - 3Kg.
7. WITHDRAWAL FORCE :0.3 - 2Kg.
8. AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
9. AFTER HUMIDITY TEST, INSULATION RESISTANCE :50MΩ MIN.
10. PACKAGING : TAPE & REEL.
11. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
12. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT: ◎
13. HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING:
14. FOR LEAD-FREE PROCESS.



MATING PLUG (SCALE 3:1)



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
H	MYLAR	1	MYLAR 0.06T	GOLDEN COLOR
G	BREAK TERMINAL	1	BRASS 0.2t	GOLD PLATD OVER Ni 60u"Min.
F	SHUNT TERMINAL-A	1	BRASS 0.2t	GOLD PLATD OVER Ni 60u"Min.
E	RING SPRING	1	PHOSPHOR BRONZE 0.2t	GOLD PLATD OVER Ni 60u"Min.
D	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	GOLD PLATD OVER Ni 60u"Min.
C	EARTH	2	PHOSPHOR BRONZE 0.2t	GOLD PLATD OVER Ni 60u"Min.
B	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	GOLD PLATD OVER Ni 60u"Min.
A	BODY	1	HIGH TEMP.UL 94V-0	BLACK

UNLESS OTHERWISE SPECIFED TOLERANCES

DECIMALS: X :±0.5, X.X :±0.3, X.XX :±0.2
ANGLES: X :±2°, X.X :±1°

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

TITLE	3.5ø PHONE JACK		
DWN	Allen2009.12.10	PART NO. 2SJ3005-002211	
CHKD	Lussen2009.12.10	SCALE: 4:1	UNIT: mm
APVD	Max2009.12.10	SIZE: A3	SHEET: 1OF1 REV:C

CUSTOMER COPY

文件編號: RD-06-043-A